

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

VOLTAGE RANGE

20 to 100 Volts

CURRENT

3.0 Ampere



SMC

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.21 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

P/N(MARK)	SS32C	SS33C	SS34C	SS35C	SS36C	SS38C	SS39C	SS310C	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current At T _L =100°C	3.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80								A
Maximum Instantaneous Forward Voltage at 3.0A	0.55		0.70			0.85			V
Maximum DC Reverse Current T _a =25°C	0.1			0.02					mA
at Rated DC Blocking Voltage T _a =100°C	5			2					mA
Typical Junction Capacitance (Note1)	300								pF
Typical Thermal Resistance R _{JL} (Note 2)	10								°C/W
Operating Temperature Range T _J	-65 — +150								°C
Storage Temperature Range T _{stg}	-65 — +150								°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (SS32C THRU SS310C)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

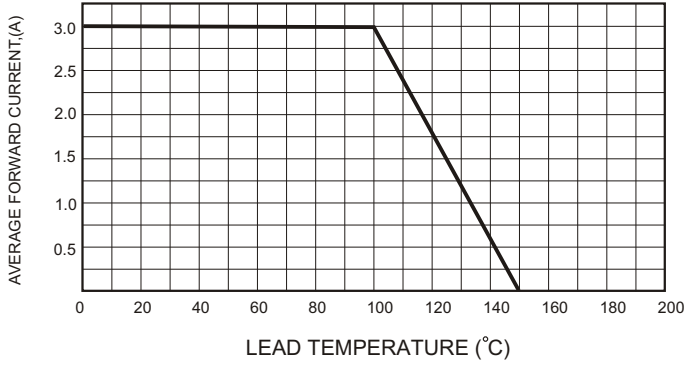


FIG.2-TYPICAL FORWARD CHARACTERISTICS

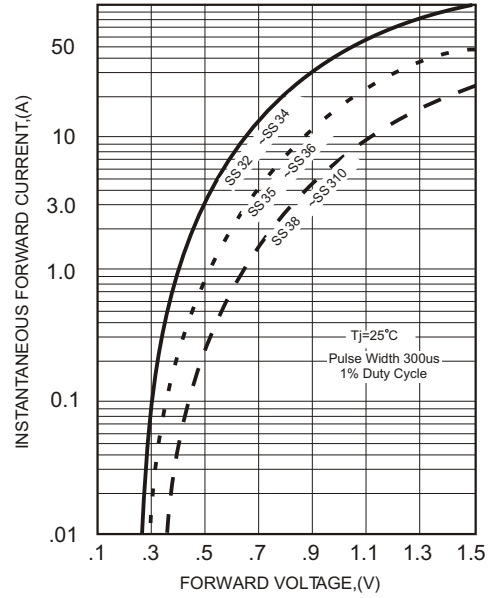


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

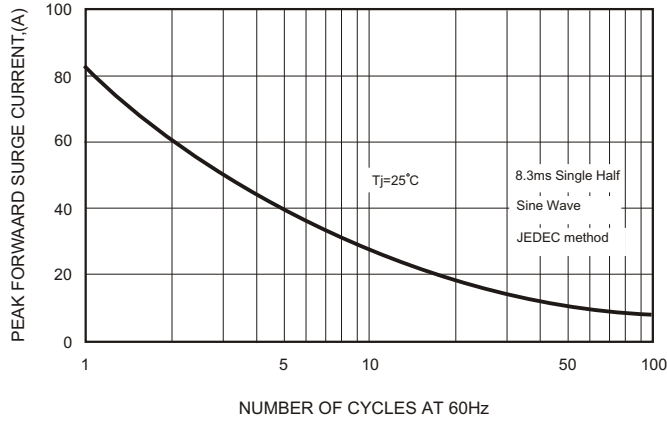


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

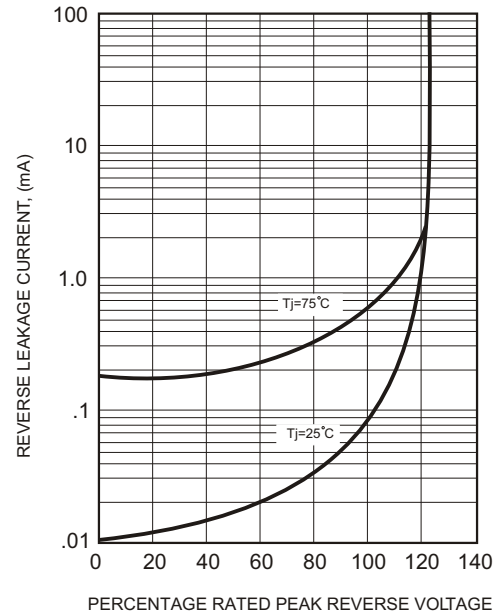
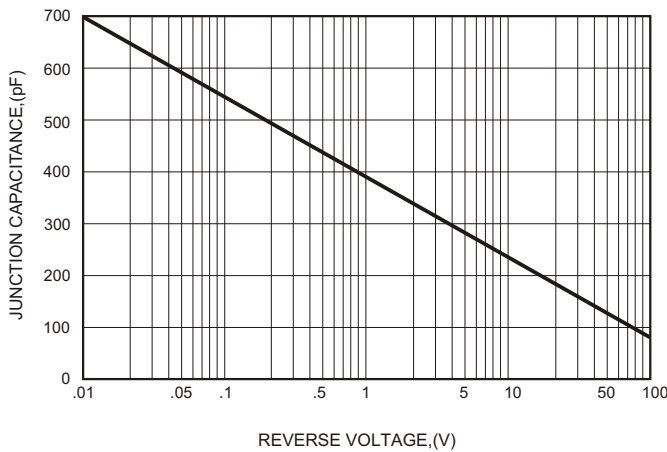
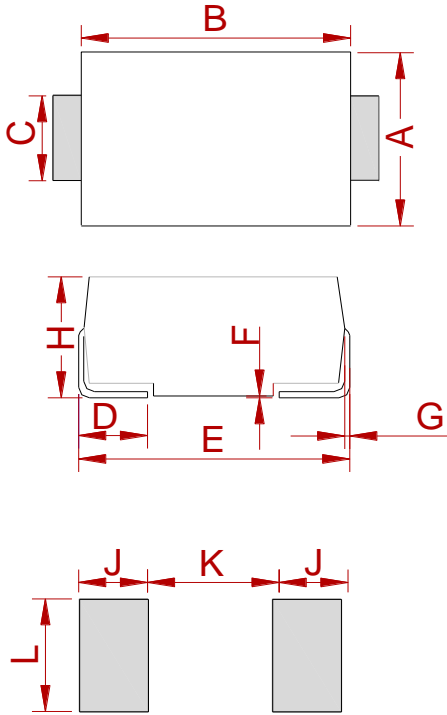


FIG.4-TYPICAL JUNCTION CAPACITANCE



PACKAGE MECHANICAL DATA



SMC

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

REEL SPECIFICATION

P/N	PKG	QTY
SS32C THRU SS310C	SMC	3000

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